



THE INSTITUTION OF ENGINEERS, MALAYSIA

Bangunan Ingenieur, Lots 60 & 62, Jalan 52/4, P.O. Box 223, Jalan Sultan, 46720 Petaling Jaya

Tel: 03-7968 4001/4002 Fax: 03-7957 7678 E-mail: sec@iem.org.my

Homepage: <http://www.iem.org.my>

PROFESSIONAL INTERVIEW WORKSHOP FOR CIVIL / ELECTRICAL / ELECTRONIC GRADUATE MEMBERS

(Organised by the Professional Interview Board, IEM)

Date : 5 September 2015 (Saturday)
Time : 2.00 pm to 5.00 pm (Refreshment will be served at 3.30 pm)
Venue : 2ND & 3RD Floor, Wisma IEM
Speakers : Ir. Tu Yong Eng (Civil)
Ir. Hoo Choon Sean (Civil)
Ir. Chen Harn Shean (Civil)
Ir. Tar Singh s/o Balwant Singh (Electrical / Electronic)
Ir. Kok Yee Hin (Electrical / Electronic)
Ir. Lee Boon Chong (Electrical / Electronic)

BEM Approved
PDP Hours: 2.5
IEM15/PDP/007/W

REGISTRATION FEE		
Grade	Normal	Online
IEM member	RM30	RM20
Non IEM member	RM120	RM100

The workshop will cover the following:

- Purpose of Professional Interview
- Guidelines for Professional Interview
- Presentation at the Interview
 - Submission of Reports
 - Oral Interview
 - Essay writing
- Code of Ethics



The workshop is to serve as a clarification session for “would-be” Corporate Members. All graduate members with more than 3 years experience are encouraged to attend the workshop and to apply for the Professional Interview thereafter. Members who are interested to participate are requested to return the reply slip to the IEM Secretariat by **31 August 2015** together with the commitment fee payable to *The Institution of Engineers, Malaysia*. Please note that the **commitment fee must be settled prior to the workshop.**

Ir. Tu Yong Eng
Chairman
Professional Interview Board

Reply Slip (Fax to: 03- 7957 7678)

Chairman
Professional Interview Board
The Institution of Engineers, Malaysia

PROFESSIONAL INTERVIEW WORKSHOP

I wish to participate in the Professional Interview workshop on **5 September 2015 (Saturday)**. I enclose herewith a cheque No./Cash..... for the amount of..... as my commitment fee for the workshop.

Name of Member: M'ship No:

Address: Grade:

..... Email:

..... Tel (H/P):

Company's Name: I/C No. of Participant:

Signature

(Photostat copies are acceptable)

Date